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U.S. PATENT DOCUMENTS

EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
JL	A1	3,397,278	8/13/68	Pomerantz			
	A2	3,417,459	12/24/68	Pomerantz			
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	A4	5,544,772	8/13/96	Soave et al.			7/25/95
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JL	B1	DE 4426288 A1	4/18/96	DE			7/26/94		N
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